

ABSTRACT OF THE DISCLOSURE

An array of solder balls is formed on a first substrate for interconnecting with conductive sites on another substrate. A ball pickup tool picks up balls with a vacuum suction from a fluidized ball reservoir and utilizes a puff of gas to release the solder ball(s) carried thereon to conductive sites of a substrate for bonding thereto. In another embodiment, the bond pads of a substrate are coated with a flux or adhesive and lowered into a fluidized ball reservoir for direct attachment of solder balls.

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